

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

**1. (Currently Amended)** A multi-layer printed circuit board for mounting electronic parts on it, comprising:

a first signal layer formed on an obverse surface of said multi-layer printed circuit board;

a ground layer arranged at a position next to said first signal layer;

an electronic power source layer arranged at a position next to said ground layer; and

a second signal layer formed on a reverse surface of said multi-layer printed circuit board;

wherein a first ground pattern is formed around a peripheral area of said first signal layer, while a second ground pattern is formed around a peripheral area of said second signal layer; and

wherein said first ground pattern and said second ground pattern are electrically coupled to each other by a plurality of

through holes, and said multi-layer printed circuit board is installed on an electro-conductive housing in such a manner that a substantially whole area of said second ground pattern electrically contacts a mounting area of said electro-conductive housing, said mounting area being an electro-conductive area continuously coupled to said electro-conductive housing; and wherein a snubber circuit, being a serial connection of a resistor and a capacitor, is coupled between said ground layer and said electronic power source layer.

**Claim 2. (Cancelled)**

**3. (Currently Amended)** A method for installing a multi-layer printed circuit board on an electro-conductive housing, said multi-layer printed circuit, on which electronic parts are mounted, comprising a first signal layer formed on an obverse surface of said multi-layer printed circuit board, a ground layer arranged at a position next to said first signal layer, an electronic power source layer arranged at a position next to said ground layer, and a second signal layer formed on a reverse surface of said multi-layer printed circuit board, said method

comprising the steps of:

forming a first ground pattern around a peripheral area of said first signal layer;

forming a second ground pattern around a peripheral area of said second signal layer;

coupling electrically said first ground pattern to said second ground pattern with a plurality of through holes; **[[and]]**

coupling a snubber circuit, being a serial connection of a resistor and a capacitor, between said ground layer and said electronic power source; and

mounting said multi-layer printed circuit board on a mounting area of said electro-conductive housing in such a manner that a substantially whole area of said second ground pattern electrically contacts said mounting area of said electro-conductive housing, said mounting area being an electro-conductive area continuously coupled to said electro-conductive housing.

**4. (Original)** The method of claim 3,

wherein said mounting area of said electro-conductive housing is formed in a protruded shape, so that said electronic

parts are held by said multi-layer printed circuit board without physically touching said electro-conductive housing.

**5. (Original)** The method of claim 3,

wherein an inner area surrounded by said mounting area of said electro-conductive housing is formed in a concaved shape, so that said electronic parts are held by said multi-layer printed circuit board without physically touching said electro-conductive housing, and said inner area is opposed against said reverse surface of said multi-layer printed circuit board.

**6. (Original)** The method of claim 3,

wherein a part of an inner area surrounded by said mounting area of said electro-conductive housing is formed in a concaved shape, so that an electronic part, being one of said electronic parts, is held by said multi-layer printed circuit board without physically touching said electro-conductive housing, and said inner area is opposed against said reverse surface of said multi-layer printed circuit board.

**7. (Currently Amended)** The method of claim 3,

wherein an inner area surrounded by said mounting area of said electro-conductive housing is a flat plane continued from said mounting area, so that said multi-layer printed circuit board is mounted on said electro-conductive housing with ~~[[a]]~~ an insulation layer between said inner area and said ~~flat plane~~ multi-layer printed circuit board, and said inner area is opposed against said reverse surface of said multi-layer printed circuit board.

**8. (Currently Amended)** A method for installing a multi-layer printed circuit board on an electro-conductive housing, said multi-layer printed circuit, on which electronic parts are mounted, comprising a first signal layer formed on an obverse surface of said multi-layer printed circuit board, a ground layer arranged at a position next to said first signal layer, an electronic power source layer arranged at a position next to said ground layer, and a second signal layer formed on a reverse surface of said multi-layer printed circuit board, said method comprising the steps of:

forming a first ground pattern around a peripheral area of said first signal layer;

forming a second ground pattern around a peripheral area of said second signal layer;

coupling electrically said first ground pattern to said second ground pattern with a plurality of through holes; ~~[[and]]~~

~~coupling a snubber circuit, being a serial connection of a resistor and a capacitor, between said ground layer and said electronic power source; and~~

mounting said multi-layer printed circuit board on a mounting area of said electro-conductive housing in such a manner that a substantially whole area of said first ground pattern is electrically coupled to said electro-conductive housing through an electro-conductive member.

**9. (Original)** The method of claim 8,

wherein said multi-layer printed circuit board is held between said electro-conductive member and said electro-conductive housing by fastening them with screws, so that said electro-conductive member press-contacts said first ground pattern while press-contacting said electro-conductive housing.

**10. (Original)** The method of claim 8,

wherein an inner area surrounded by said mounting area of said electro-conductive housing is formed in a concaved shape, so that said electronic parts are held by said multi-layer printed circuit board without physically touching said electro-conductive housing, and said inner area is opposed against said reverse surface of said multi-layer printed circuit board.

**11. (Original)** The method of claim 8,

wherein a part of an inner area surrounded by said mounting area of said electro-conductive housing is formed in a concaved shape, so that an electronic part, being one of said electronic parts, is held by said multi-layer printed circuit board without physically touching said electro-conductive housing, and said inner area is opposed against said reverse surface of said multi-layer printed circuit board.

**12. (Currently amended)** The method of claim 8,

wherein an inner area surrounded by said mounting area of said electro-conductive housing is a flat plane continued from said mounting area, so that said multi-layer printed circuit

board is mounted on said electro-conductive housing with [[a]] an insulation layer between said inner area and said ~~flat plane~~ multi-layer printed circuit board, and said inner area is opposed against said reverse surface of said multi-layer printed circuit board.